

PRODUCT SPECIFICATION

4.3” IPS TFT LCD MODULE
MODEL: YDP LCD I 430 SR 001



- < ◇ > Preliminary Specification
- < ◆ > Finally Specification

CUSTOMER’S APPROVAL	
CUSTOMER :	
SIGNATURE:	DATE:

APPROVED	PM	PD	PREPARED
BY	REVIEWED	REVIEWED	BY
<div>TFT</div> <div>Y. B</div> <div>20240227</div>	<div>TFT</div> <div>S. G. H</div> <div>20240227</div>	<div></div>	<div>TFT</div> <div>Funny</div> <div>20240227</div>

knitter-switch

Revision History

Revision	Date	Originator	Detail	Remarks
1.0	2024.02.27	ZFY	Initial Release	

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	4.3"	
LCD type	IPS TFT	
Display Mode	Transmissive/Normal Black	
Resolution	800 RGB x 480	Pixels
View Direction	Full view	Best Image
Module Outline	105.5 (H) x 67.2(V) x 2.9(T) (Note1)	mm
Active Area	95.04 (H) x 53.86(V)	mm
Pixel Size	118.8 (H) x 112.2(V)	um
Pixel Arrangement	RGB Vertical Stripe	
Display Colors	16.7M	
Driver IC	ST7262E43	-
Interface	24-bit RGB + 3-SPI interface	
With or Without Touch Panel	Without	
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	°C
Weight	TBD	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

GND=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VDD	-0.3	4.0	V
Storage temperature	T _{STG}	-30	80	°C
Operating temperature	T _{OP}	-20	70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	VDD	3.1	3.3	3.6	V
Logic-High Input Voltage	V _{IH}	0.7VDD	-	VDD	V
Logic-Low Input Voltage	V _{IL}	GND	-	0.3VDD	V
Logic-High Output Voltage	V _{OH}	VDD-0.4	-	VDD	V
Logic-Low Output Voltage	V _{OL}	GND	-	GND+0.4	V
Current Consumption All white	I _{DD}	-	TBD	-	mA

5. Backlight Characteristics

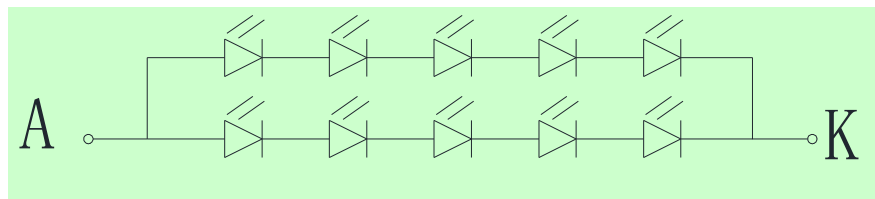
5.1. Backlight Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Backlight Voltage	V _{LED}	Ta=25 °C, I _F =20mA/LED	(14)	16	(17)	V
Backlight Current	I _{LED}	Ta=25 °C, V _F =3.2V/LED	-	40	-	mA
Power dissipation	P _D		-	640	-	mW
Uniformity	Avg		-	80	-	%
LED working life(25°C)	-		-	30000	-	Hrs
Drive method	Constant current					
LED Configuration	10 White LEDs (5 LEDs in one string and 2 groups in parallel)					

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25±2 °C, 60%RH±5%, I_F=20mA/LED.

5.2. Backlighting circuit



6. Optical Characteristics

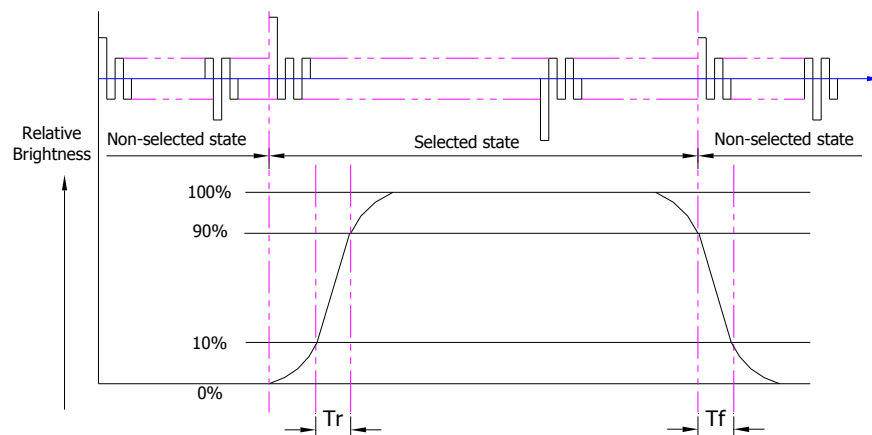
6.1. Optical Characteristics

Ta=25°C, VDD=3.3V

Backlight On (Transmissive Mode)	Item		Symbol	Condition	Specification			Unit
					Min.	Typ.	Max.	
	Luminance on TFT(I_f =20mA/LED)		Lv	Normally viewing angle $\theta_x = \varphi_y = 0^\circ$	288	360	-	cd/m ²
	Contrast ratio(See 6.3)		CR		1000	1500	-	
	Response time (See 6.2)		T _R +T _F		-	30	40	ms
	Chromaticity Transmissive (See 6.5)	Red	X _R			(0.613)		
			Y _R			(0.347)		
		Green	X _G			(0.339)		
			Y _G			(0.294)		
		Blue	X _B			(0.153)		
			Y _B			(0.125)		
		White	X _W			(0.314)		
			Y _W			(0.335)		
	Viewing Angle (See 6.4)	Horizontal	θ _x +	Center CR≥10	70	80	-	Deg.
			θ _x -		70	80	-	
		Vertical	φ _y +		70	80	-	
			φ _y -		70	80	-	
NSTC			Θ=0°	55	60		%	

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

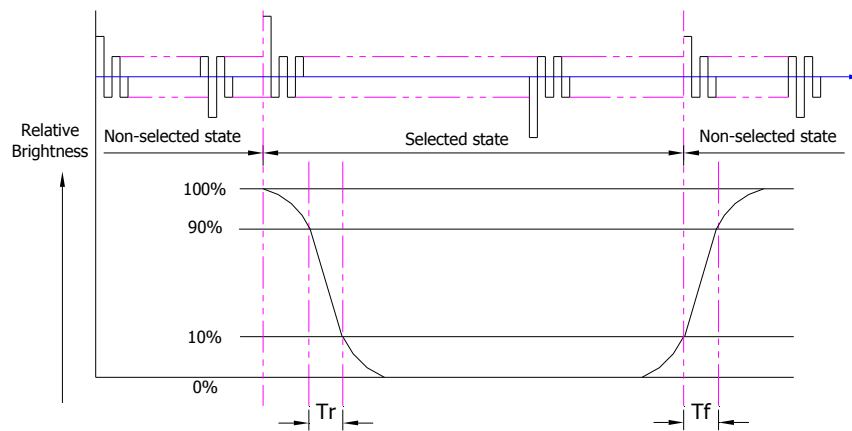


T_r is the time it takes to change from non-selected state with relative luminance 10% to selected state with relative luminance 90%;

T_f is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change from non-selected state with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

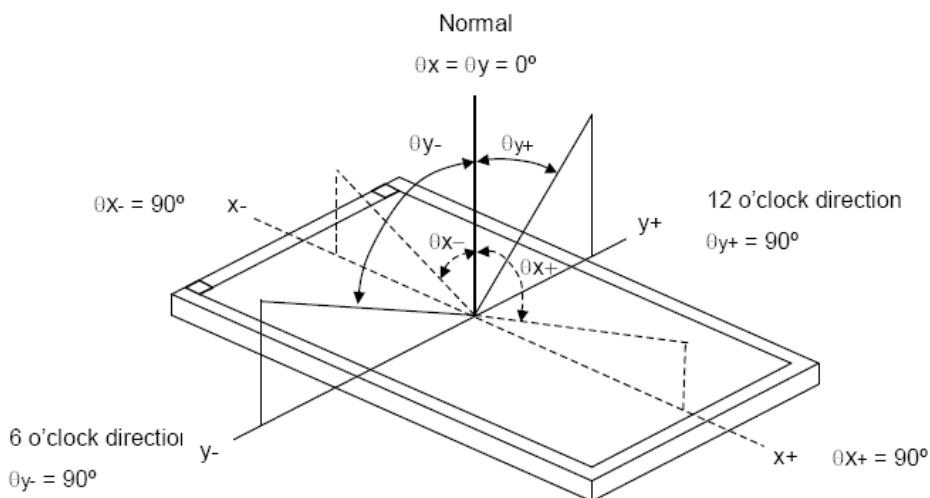
6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test pattern	A: All Pixels white
	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



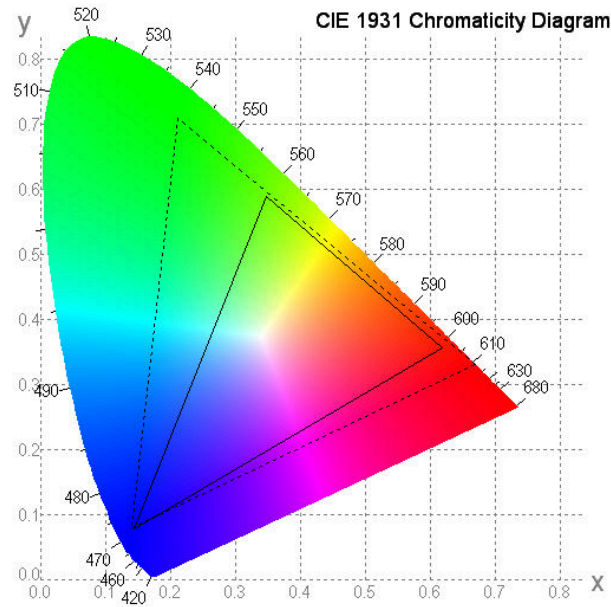
Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.6. Definition of Surface Luminance, Uniformity and Transmittance

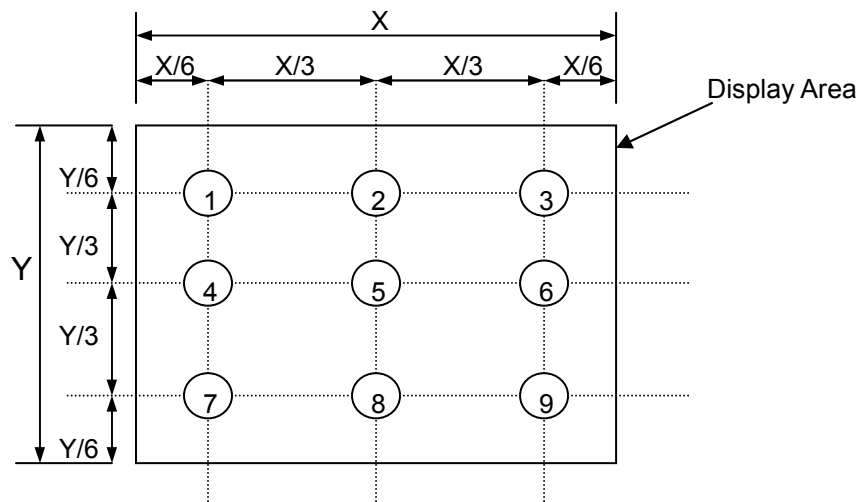
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

6.6.1. Surface Luminance: $L_v = \text{average } (L_{P1}:L_{P9})$

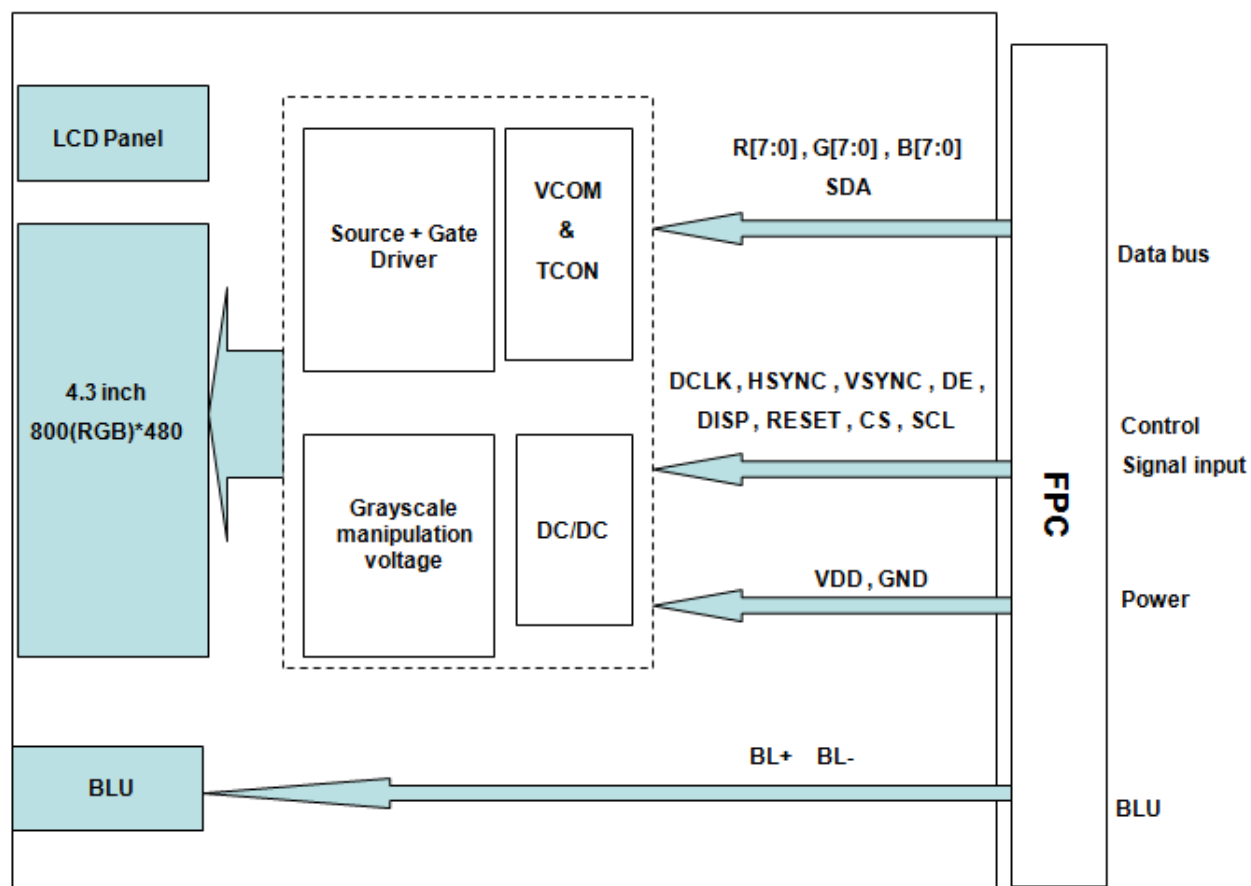
6.6.2. Uniformity = Minimal ($L_{P1}:L_{P9}$) / Maximal ($L_{P1}:L_{P9}$) * 100%

6.6.3. Transmittance = L_v on LCD / L_v on Backlight * 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply

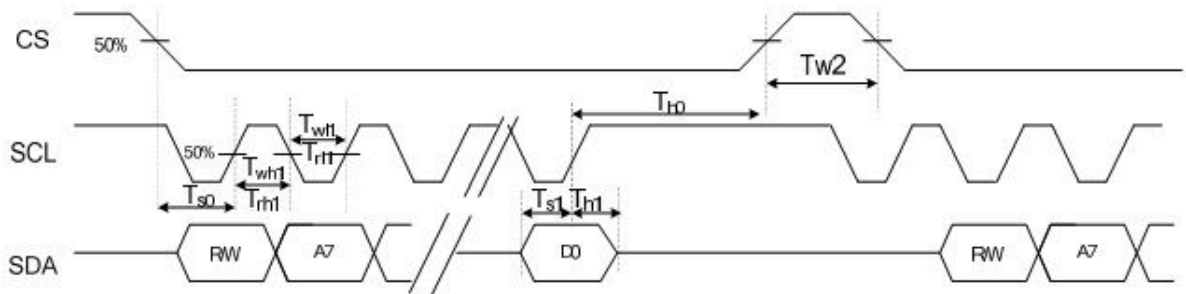


8. Interface Pins Definition

No.	Symbol	Function	Remark
1	BL-	LED Cathode	
2	BL+	LED Anode	
3	GND	Ground	
4	VDD	Power Supply	
5	R0	Red data	
6	R1	Red data	
7	R2	Red data	
8	R3	Red data	
9	R4	Red data	
10	R5	Red data	
11	R6	Red data	
12	R7	Red data	
13	G0	Green data	
14	G1	Green data	
15	G2	Green data	
16	G3	Green data	
17	G4	Green data	
18	G5	Green data	
19	G6	Green data	
20	G7	Green data	
21	B0	Blue data	
22	B1	Blue data	
23	B2	Blue data	
24	B3	Blue data	
25	B4	Blue data	
26	B5	Blue data	
27	B6	Blue data	
28	B7	Blue data	
29	GND	Ground	
30	DCLK	Pixel clock input pin	
31	DISP	Set the display mode. L: standby mode; H: normal display mode	
32	HSYNC	Horizontal sync signal	
33	VSYNC	Vertical sync signal	
34	DE	Data input enable applied to the RGB interface	
35	RESET	Global reset pin	
36	GND	Ground	
37	SCL	Serial communication clock input	
38	SDA	Serial communication data input and output	
39	CS	Serial communication chip selection.	
40	OTP	Reserved for OTP test only, please leave it open.	

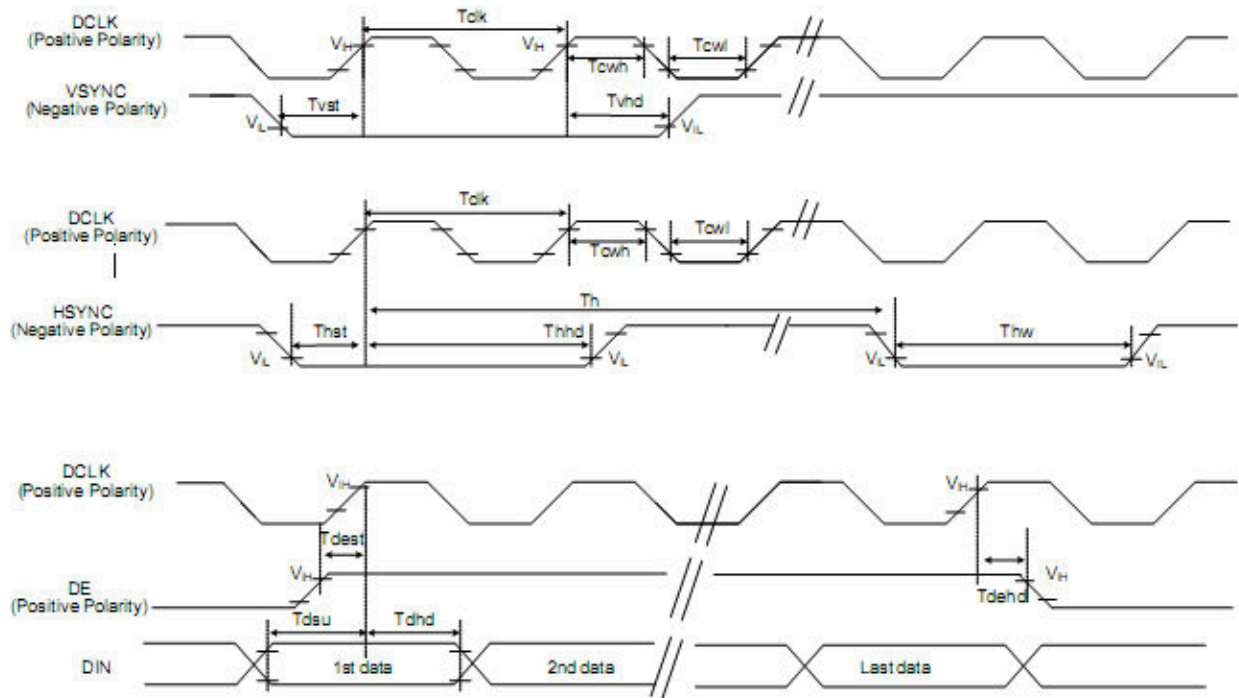
9. AC Characteristics

9.1. System Bus Timing for 3-wire SPI Interface



Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
CS Input Setup Time	T_{so}	50	-	-	ns	
Serial Data Input Setup Time	T_{s1}	50	-	-	ns	
CS Input Hold Time	T_{ho}	50	-	-	ns	
Serial Data Input Hold Time	T_{h1}	50	-	-	ns	
SCL Write Pulse High Width	T_{wh1}	50	-	2000	ns	
SCL Write Pulse Low Width	T_{wl1}	50	-	2000	ns	
SCL Read Pulse High Width	T_{rh1}	300	-	2000	ns	
SCL Read Pulse Low Width	T_{rl1}	300	-	2000	ns	
CS Pulse High Width	T_{w2}	400	-	-	ns	

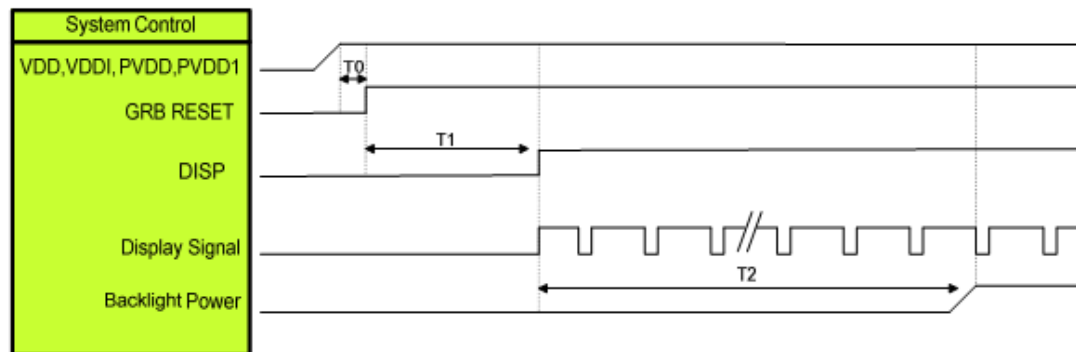
9.2. System Bus Timing for RGB Interface



Item	Symbol	Min.	Typ.	Max.	Unit	Conditions
CLK Pulse Duty	T_{clk}	40	50	60	%	
VSYNC Setup Time	T_{vst}	10	-	-	ns	
VSYNC Hold Time	T_{vhd}	10	-	-	ns	
HSYNC Setup Time	T_{hst}	10	-	-	ns	
HSYNC Hold Time	T_{hhd}	10	-	-	ns	
Data Setup Time	T_{dsu}	10	-	-	ns	
Data Hold Time	T_{dhhd}	10	-	-	ns	
DE Setup Time	T_{dest}	10	-	-	ns	
DE Hold Time	T_{dehd}	10	-	-	ns	

10. Power on/off Sequence

1) Power On Sequence

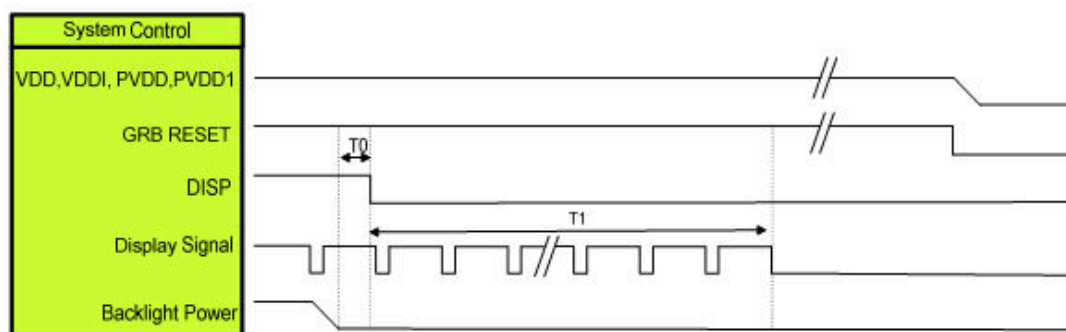


Symbol	Description	Min. Time	Unit
T0	System power stability to GRB RESET signal	0	ms
T1	GRB RESET= "High" to DISP="High"	10	ms
T2	Display Signal output to Backlight Power on	250	ms

Note :

1. When DISP pull "H" or "L", IC will execute the internal power on or power off procedures .Please be careful about the timing of DISP and do not interrupt it during power on or power off procedure, otherwise unexpected errors will occur.
2. RGB interface Display signal: DCLK; VSYNC; HSYNC; DE; DR[7:0]; DG[7:0]; DB[7:0]
3. LVDS interface Display signal: DCLK P/N; RX[3:0] P/N

2) Power Off Sequence



Symbol	Description	Min. Time	Unit
T0	Backlight Power off to DISP="Low"	5	ms
T1	DISP="Low" to IC internal voltage discharge complete	100	ms

Note :

1. When DISP pull "H" or "L", IC will execute the internal power on or power off procedures. Please be careful about the timing of DISP and do not interrupt it during power on or power off procedure, otherwise unexpected errors will occur.
2. RGB interface Display signal: DCLK; VSYNC; HSYNC; DE; DR[7:0]; DG[7:0]; DB[7:0]
3. LVDS interface Display signal: DCLK P/N; RX[3:0] P/N

11. Quality Assurance

11.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

11.2.Standard for Quality Test

11.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

11.2.2. Sampling Criteria:

Visual inspection: AQL 1.5.

Electrical functional: AQL 0.65.

11.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

11.3.Nonconforming Analysis & Disposition

11.3.1. Nonconforming analysis:

11.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.

11.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

11.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.

11.3.2. Disposition of nonconforming:

11.3.2.1. Non-conforming product over PPM level will be replaced.

11.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

11.4.Agreement Items

Shall negotiate with customer if the following situation occurs:

11.4.1. There is any discrepancy in standard of quality assurance.

11.4.2. Additional requirement to be added in product specification.

11.4.3. Any other special problem.

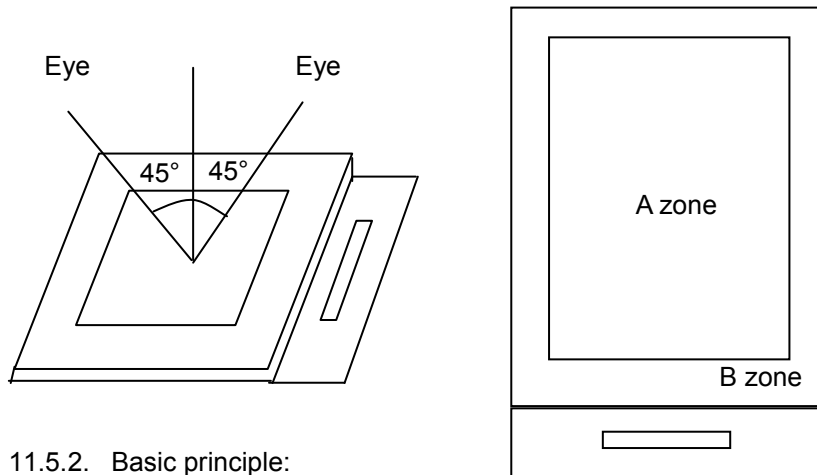
11.5.Standard of the Product Visual Inspection

11.5.1. Appearance inspection:

11.5.1.1. The inspection must be under illumination about 1000 - 1500 lx, and the distance of view must be at 30cm \pm 2cm .

11.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

11.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,

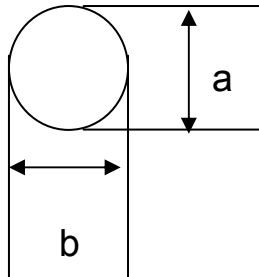


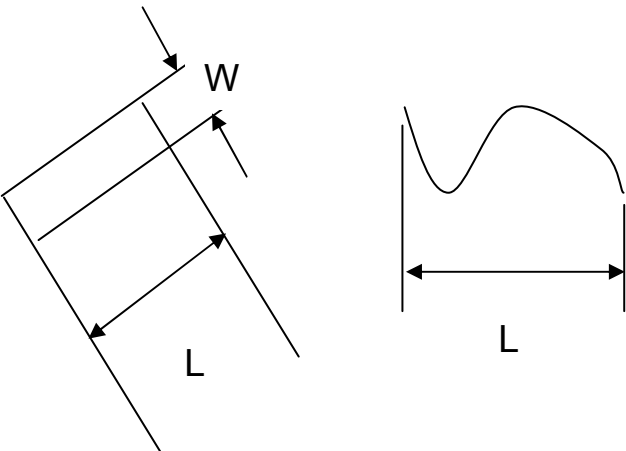
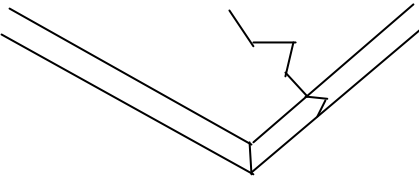
11.5.2. Basic principle:

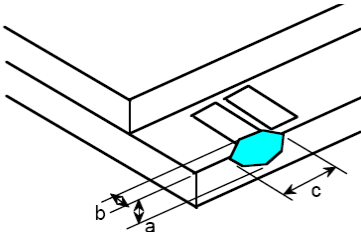
11.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

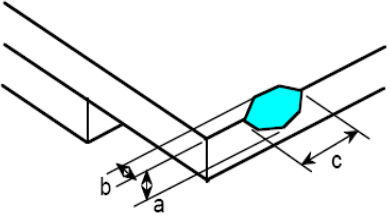
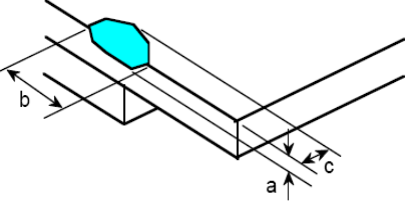
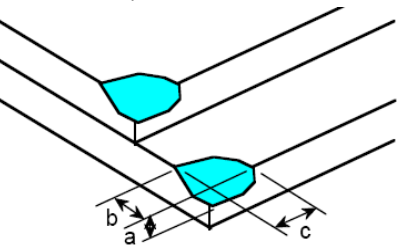
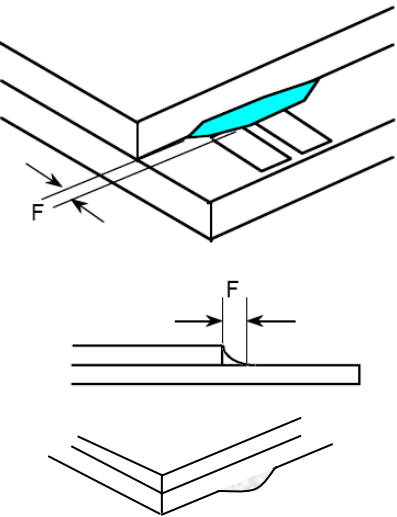
11.5.2.2. New item must be added on time when it is necessary.

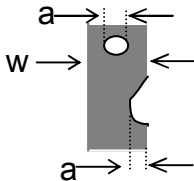
11.6. Inspection Specification

No.	Item	Criteria (Unit: mm)																					
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	 $\varphi = (a + b) / 2$ Distance between 2 defects should more than 5mm apart.	<table><tr><th>Size \ Area</th><th colspan="2">Acc. Qty</th></tr><tr><td>$\varphi \leq 0.10$</td><td colspan="2">Ignore</td></tr><tr><td>$0.10 < \varphi \leq 0.15$</td><td colspan="2">2</td></tr><tr><td>$0.15 < \varphi \leq 0.25$</td><td colspan="2">1</td></tr><tr><td>$0.25 < \varphi$</td><td colspan="2">0</td></tr><tr><td>Total</td><td>2</td><td>no include $\varphi \leq 0.10$</td></tr></table>			Size \ Area	Acc. Qty		$\varphi \leq 0.10$	Ignore		$0.10 < \varphi \leq 0.15$	2		$0.15 < \varphi \leq 0.25$	1		$0.25 < \varphi$	0		Total	2	no include $\varphi \leq 0.10$
			Size \ Area	Acc. Qty																			
$\varphi \leq 0.10$	Ignore																						
$0.10 < \varphi \leq 0.15$	2																						
$0.15 < \varphi \leq 0.25$	1																						
$0.25 < \varphi$	0																						
Total	2	no include $\varphi \leq 0.10$																					
02	Electrical Defect (Minor defect)	<table><tr><td></td><td>Display Area</td><td>Total</td><td rowspan="4">Note1</td></tr><tr><td>Bright dot</td><td>0</td><td>0</td></tr><tr><td>Dark dot</td><td>$N \leq 2$</td><td>$N \leq 2$</td></tr><tr><td>Total dot</td><td>$N \leq 2$</td><td>$N \leq 2$</td></tr><tr><td>Mura</td><td colspan="2">Not visible through 5% ND filters.</td><td>Note2</td></tr></table> Remark: 1. Bright dot caused by scratch and foreign object accords to item 1.					Display Area	Total	Note1	Bright dot	0	0	Dark dot	$N \leq 2$	$N \leq 2$	Total dot	$N \leq 2$	$N \leq 2$	Mura	Not visible through 5% ND filters.		Note2	
	Display Area	Total	Note1																				
Bright dot	0	0																					
Dark dot	$N \leq 2$	$N \leq 2$																					
Total dot	$N \leq 2$	$N \leq 2$																					
Mura	Not visible through 5% ND filters.		Note2																				

03	Black and White line Scratch Foreign material (Line type) (Minor defect)	 <table border="1" data-bbox="564 748 1192 1055"> <thead> <tr> <th>Length</th><th>Width</th><th>Acc. Qty</th></tr> </thead> <tbody> <tr> <td>/</td><td>$W \leq 0.03$</td><td>Ignore</td></tr> <tr> <td>$L \leq 2.5$</td><td>$0.03 < W \leq 0.05$</td><td>3</td></tr> <tr> <td>$L \leq 2.5$</td><td>$0.05 < W \leq 0.10$</td><td>2</td></tr> <tr> <td>/</td><td>$0.1 < W$</td><td>0</td></tr> <tr> <td colspan="2">Total</td><td>3</td></tr> </tbody> </table> <p>Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.</p>	Length	Width	Acc. Qty	/	$W \leq 0.03$	Ignore	$L \leq 2.5$	$0.03 < W \leq 0.05$	3	$L \leq 2.5$	$0.05 < W \leq 0.10$	2	/	$0.1 < W$	0	Total		3
Length	Width	Acc. Qty																		
/	$W \leq 0.03$	Ignore																		
$L \leq 2.5$	$0.03 < W \leq 0.05$	3																		
$L \leq 2.5$	$0.05 < W \leq 0.10$	2																		
/	$0.1 < W$	0																		
Total		3																		
04	Glass Crack (Minor defect)	 <p>Crack is potential to enlarge, any type is not allowed.</p>																		

05	Glass Chipping Pad Area: (Minor defect)		<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>3</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	3	$a < \text{Glass Thickness}$	
	Length and Width	Acc. Qty									
$c > 3.0, b < 1.0$	1										
$c < 3.0, b < 1.0$	3										
$a < \text{Glass Thickness}$											

06	<p>Glass Chipping Rear of Pad Area: (Minor defect)</p> 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
07	<p>Glass Chipping Except Pad Area: (Minor defect)</p> 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c > 3.0, b < 1.0$</td><td>1</td></tr><tr><td>$c < 3.0, b < 1.0$</td><td>2</td></tr><tr><td>$c < 3.0, b < 0.5$</td><td>4</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
08	<p>Glass Corner Chipping: (Minor defect)</p> 	<table><tr><th>Length and Width</th><th>Acc. Qty</th></tr><tr><td>$c < 3.0, b < 3.0$</td><td>Ignore</td></tr><tr><td colspan="2">$a < \text{Glass Thickness}$</td></tr></table>	Length and Width	Acc. Qty	$c < 3.0, b < 3.0$	Ignore	$a < \text{Glass Thickness}$					
Length and Width	Acc. Qty											
$c < 3.0, b < 3.0$	Ignore											
$a < \text{Glass Thickness}$												
09	<p>Glass Burr: (Minor defect)</p> 	<table><tr><th>Length</th><th>Acc. Qty</th></tr><tr><td>$F < 1.0$</td><td>Ignore</td></tr></table> <p>Glass burr don't affect assemble and module dimension.</p>	Length	Acc. Qty	$F < 1.0$	Ignore						
Length	Acc. Qty											
$F < 1.0$	Ignore											

10	FPC Defect: (Minor defect) 	10.1 Dent, pinhole width $a < w/3$. (w: circuitry width.) 10.2 Open circuit is unacceptable. 10.3 No oxidation, contamination and distortion.										
11	Bubble on Polarizer (Minor defect)	<table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$\phi \leq 0.20$</td><td>Ignore</td></tr><tr><td>$0.20 < \phi \leq 0.30$</td><td>4</td></tr><tr><td>$0.30 < \phi \leq 0.50$</td><td>1</td></tr><tr><td>$0.50 < \phi$</td><td>None</td></tr></table>	Diameter	Acc. Qty	$\phi \leq 0.20$	Ignore	$0.20 < \phi \leq 0.30$	4	$0.30 < \phi \leq 0.50$	1	$0.50 < \phi$	None
Diameter	Acc. Qty											
$\phi \leq 0.20$	Ignore											
$0.20 < \phi \leq 0.30$	4											
$0.30 < \phi \leq 0.50$	1											
$0.50 < \phi$	None											
12	Dent on Polarizer (Minor defect)	<table><tr><th>Diameter</th><th>Acc. Qty</th></tr><tr><td>$\phi \leq 0.20$</td><td>Ignore</td></tr><tr><td>$0.20 < \phi \leq 0.30$</td><td>4</td></tr><tr><td>$0.30 < \phi \leq 0.50$</td><td>1</td></tr><tr><td>$0.50 < \phi$</td><td>None</td></tr></table>	Diameter	Acc. Qty	$\phi \leq 0.20$	Ignore	$0.20 < \phi \leq 0.30$	4	$0.30 < \phi \leq 0.50$	1	$0.50 < \phi$	None
Diameter	Acc. Qty											
$\phi \leq 0.20$	Ignore											
$0.20 < \phi \leq 0.30$	4											
$0.30 < \phi \leq 0.50$	1											
$0.50 < \phi$	None											
13	Bezel	13.1 No rust, distortion on the Bezel. 13.2 No visible fingerprints, stains or other contamination.										
14	PCB	14.1 No distortion or contamination on PCB terminals. 14.2 All components on PCB must same as documented on the BOM/component layout. 14.3 Follow IPC-A-600F.										
15	Soldering	Follow IPC-A-610C standard										
16	Electrical Defect (Major defect)	The below defects must be rejected. 16.1 Missing vertical / horizontal segment, 16.2 Abnormal Display. 16.3 No function or no display. 16.4 Current exceeds product specifications. 16.5 LCD viewing angle defect. 16.6 No Backlight. 16.7 Dark Backlight. 16.8 Touch Panel no function.										

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

11.7. Classification of Defects

- 11.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 11.7.2. Two minor defects are equal to one major in lot sampling inspection.

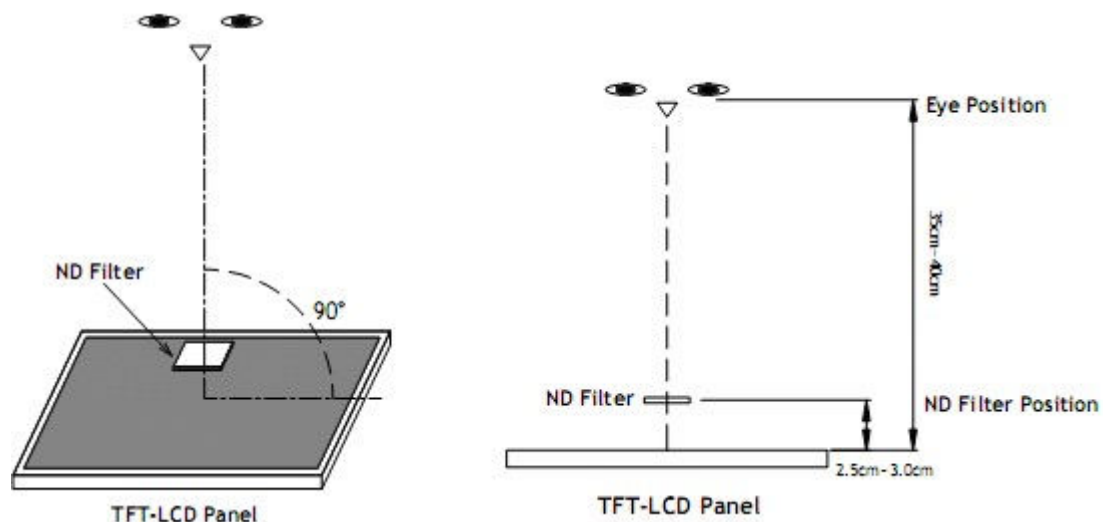
11.8. Identification/marketing criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

11.9. Packing

- 11.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 11.9.2. Modules inside package box should have compliant mark.
- 11.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is $350\text{mm} \pm 50\text{mm}$.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is $350\text{mm} \pm 50\text{mm}$.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

12. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70 °C, 96Hrs	2	GB/T2423.2-2008
2	Low Temperature Operating	-20 °C, 96Hrs	2	GB/T2423.1-2008
3	High Humidity Storage	50 °C, 90%RH, 96Hrs	2	GB/T2423.3-2016
4	High Temperature Storage	80 °C, 96Hrs	2	GB/T2423.2-2008
5	Low Temperature Storage	-30 °C, 96Hrs	2	GB/T2423.1-2008
6	Thermal Cycling Test Storage	-20 °C, 60min ~ 70 °C, 60min, 20 cycles.	2	GB/T2423.22-2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14-2009
8	Electrical Static Discharge	Air: ±4KV 150pF/330 Ω 5 times Contact: ±2KV 150pF/330 Ω 5 times	2	GB/T17626.2-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8-1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

13. Precautions and Warranty

13.1. Safety

- 13.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 13.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

13.2. Handling

- 13.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 13.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

13.3. Storage

- 13.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 13.3.2. Strong light exposure causes degradation of polarizer and color filter.

13.4. Metal Pin (Apply to Products with Metal Pins)

13.4.1. Pins of LCD and Backlight

- 13.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

13.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

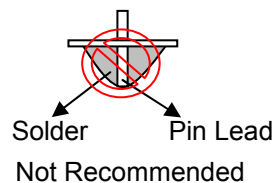
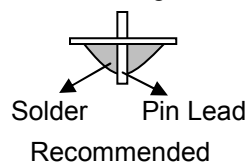
Maximum Solder Temperature: 370℃

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20℃

Typical Soldering Time: ≤3s

13.4.1.3. Solder Wetting



13.4.2. Pins of EL

- 13.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

- 13.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

13.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290℃

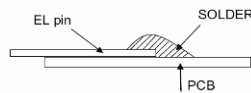
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body): 2.0mm

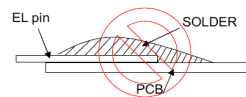
- 13.4.2.4. No horizontal press on the EL leads during soldering.

- 13.4.2.5. 180° bend EL leads three times is not allowed.
-

13.4.2.6. Solder Wetting

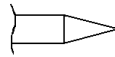


Recommended

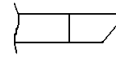


Not Recommended

13.4.2.7. The type of the solder iron:

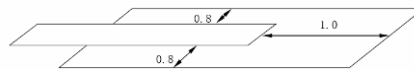


Recommended



Not Recommended

13.4.2.8. Solder Pad



13.5. Operation

- 13.5.1. Do not drive LCD with DC voltage
- 13.5.2. Response time will increase below lower temperature
- 13.5.3. Display may change color with different temperature
- 13.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear “fractured”.
- 13.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 13.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 13.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 13.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

13.6. Static Electricity

- 13.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 13.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 13.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

13.7. Limited Warranty

- 13.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 13.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 13.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

14. Packaging

TBD

15. Outline Drawings

